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Attorney Docket No. IRV1.PAU.53

HHS
Patent Application

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Pepe, et al.

Application No.: 09/938,686

Filed: August 24, 2001

Title: **STACKABLE LAYERS CONTAINING
ENCAPSULATED INTEGRATED CIRCUIT
CHIPS WITH ONE OR MORE OVERLYING
INTERCONNECT LAYERS AND A METHOD
OF MAKING THE SAME**

Examiner: Unknown

Art Unit: 2811

Irvine, California
October 29, 2001

PETITION UNDER 37 CFR 1.182

Box MISSING PARTS ?

Assistant Commissioner for Patents
Washington, D.C. 20231

Pursuant to 37 CFR 1.182, and the Notice to File Missing Parts of Nonprovisional Application dated September 28, 2001, Applicants hereby supply the omitted Figures 1a and 1b and petition the United States Patent Office to assign a later filing date of these herein submitted drawings to the overall Application. A declaration referring to the omitted figures is also enclosed.

The \$130 petition fee required under 37 FR 1.17(h) is attached.

The Commissioner of Patents is authorized to charge any amount due, or credit any overpayment, to Deposit Account No. 01-1960. A duplicate copy of this paper is enclosed.

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By Angela Williams


Signature
October 30, 2001

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